

L Number	Hits	Search Text	DB	Time stamp
1	56085	(wafer or substrate or board) with (align\$4 near (mark\$3 or cod\$3) or align\$4)	USPAT	2004/05/16 16:06
2	3132	(wafer or substrate or board) with (align\$4 near (mark\$3 or cod\$3) )	USPAT	2004/05/16 16:07
3	2818	((wafer or substrate or board) with (align\$4 near (mark\$3 or cod\$3) )) and (semiconductor or die or chip or IC)	USPAT	2004/05/16 16:07
4	5	bare near (wafer or substrate or board) with (align\$4 near (mark\$3 or cod\$3) )	USPAT	2004/05/16 16:32
5	14	"5952694"	USPAT	2004/05/16 17:15
6	998	257/797	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/16 17:33
7	460	257/798	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/16 17:33